

# Molding Type Module IGBT, 2-in-1 Package, 1200 V and 200 A



PRODUCT SUMMARY					
$V_{CES}$	1200 V				
I <sub>C</sub> at T <sub>C</sub> = 80 °C	200 A				
$V_{CE(on)}$ (typical) at $I_C = 200$ A, 25 °C	1.90 V				
Speed	8 kHz to 30 kHz				
Package	Double INT-A-PAK				
Circuit	Half bridge				

#### **FEATURES**

- Low V<sub>CE(on)</sub> SPT+ IGBT technology
- 10 µs short circuit capability



- V<sub>CE(on)</sub> with positive temperature coefficient
- Maximum junction temperature 150 °C
- · Low inductance case
- · Fast and soft reverse recovery antiparallel FWD
- Isolated copper baseplate using DCB (Direct Copper Bonding) technology
- Material categorization: for definitions of compliance please see <a href="https://www.vishav.com/doc?99912">www.vishav.com/doc?99912</a>

#### **TYPICAL APPLICATIONS**

- UPS
- · Inverter for motor drive
- · AC and DC servo drive amplifier

### **DESCRIPTION**

Vishay's IGBT power module provides ultra low conduction loss as well as short circuit ruggedness. It is designed for applications such as general inverters and UPS.

<b>ABSOLUTE MAXIMUM RATINGS</b> (T <sub>C</sub> = 25 °C unless otherwise noted)					
PARAMETER	SYMBOL	TEST CONDITIONS	MAX.	UNITS	
Collector to emitter voltage	V <sub>CES</sub>		1200	V	
Gate to emitter voltage	V <sub>GES</sub>		± 20	V	
Callactor aurent		T <sub>C</sub> = 25 °C	360		
Collector current	I <sub>C</sub>	T <sub>C</sub> = 80 °C	200		
Pulsed collector current	I <sub>CM</sub> <sup>(1)</sup>	t <sub>p</sub> = 1 ms	400	А	
Diode continuous forward current	I <sub>F</sub>	T <sub>C</sub> = 80 °C	200		
Diode maximum forward current	I <sub>FM</sub>	t <sub>p</sub> = 1 ms	400		
Maximum power dissipation	P <sub>D</sub>	T <sub>J</sub> = 150 °C	1136	W	
Short circuit withstand time	t <sub>SC</sub>	T <sub>J</sub> = 125 °C	10	μs	
RMS isolation voltage	V <sub>ISOL</sub>	f = 50 Hz, t = 1 min	2500	V	

#### Note

<sup>(1)</sup> Repetitive rating: pulse width limited by maximum junction temperature.



IGBT ELECTRICAL SPECIFICATIONS (T <sub>C</sub> = 25 °C unless otherwise noted)						
PARAMETER	SYMBOL TEST CONDITIONS MIN. TYP.		TYP.	MAX.	UNITS	
Collector to emitter breakdown voltage	V <sub>(BR)CES</sub>	T <sub>J</sub> = 25 °C	1200	-	-	
Collector to emitter voltage	V	$V_{GE} = 15 \text{ V}, I_{C} = 200 \text{ A}, T_{J} = 25 ^{\circ}\text{C}$	-	1.90	2.35	
Collector to entitler voltage	V <sub>CE(on)</sub>	V <sub>GE</sub> = 15 V, I <sub>C</sub> = 200 A, T <sub>J</sub> = 125 °C	-	2.10	-	]
Gate to emitter threshold voltage	V <sub>GE(th)</sub>	$V_{CE} = V_{GE}$ , $I_{C} = 8.0$ mA, $T_{J} = 25$ °C	5.0	6.2	7.0	
Collector cut-off current	I <sub>CES</sub>	$V_{CE} = V_{CES}$ , $V_{GE} = 0$ V, $T_{J} = 25$ °C	-	-	5.0	mA
Gate to emitter leakage current	I <sub>GES</sub>	$V_{GE} = V_{GES}$ , $V_{CE} = 0$ V, $T_{J} = 25$ °C	-	-	400	nA

SWITCHING CHARACTERISTICS	3					
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Turn-on delay time	t <sub>d(on)</sub>		-	437	-	
Rise time	t <sub>r</sub>	]	-	75	-	ns mJ
Turn-off delay time	t <sub>d(off)</sub>	$V_{CC} = 600 \text{ V}, I_{C} = 200 \text{ A}, R_{g} = 5.1 \Omega,$	-	436	-	
Fall time	t <sub>f</sub>	$V_{GE} = \pm 15 \text{ V}, T_{J} = 25 \text{ °C}$	-	165	-	
Turn-on switching loss	E <sub>on</sub>	7	-	10.0	-	
Turn-off switching loss	E <sub>off</sub>	7	-	15.0	-	
Turn-on delay time	t <sub>d(on)</sub>		-	445	-	- ns
Rise time	t <sub>r</sub>	7	-	96	-	
Turn-off delay time	t <sub>d(off)</sub>	$V_{CC} = 600 \text{ V}, I_{C} = 200 \text{ A}, R_{q} = 5.1 \Omega,$	-	488	-	
Fall time	t <sub>f</sub>	V <sub>GE</sub> = ± 15 V, T <sub>J</sub> = 125 °C	-	258	-	
Turn-on switching loss	E <sub>on</sub>		-	15.9	-	
Turn-off switching loss	E <sub>off</sub>	7	-	22.3	-	- mJ
Input capacitance	C <sub>ies</sub>		-	14.9	-	
Output capacitance	C <sub>oes</sub>	V <sub>GE</sub> = 0 V, V <sub>CE</sub> = 25 V, f = 1.0 MHz	-	1.04	-	nF
Reverse transfer capacitance	C <sub>res</sub>	7	-	0.68	-	
SC data	I <sub>SC</sub>	$t_{sc} \leq 10 \; \mu s,  V_{GE} = 15 \; V,  T_J = 125 \; ^{\circ}C,$ $V_{CC} = 900 \; V,  V_{CEM} \leq 1200 \; V$	-	1200	-	Α
Internal gate resistance	R <sub>gint</sub>		-	1.0	-	Ω
Stray inductance	L <sub>CE</sub>		-	-	20	nΗ
Module lead resistance, terminal to chip	R <sub>CC'+EE'</sub>	T <sub>C</sub> = 25 °C	-	0.35	-	mΩ

<b>DIODE ELECTRICAL SPECIFICATIONS</b> (T <sub>C</sub> = 25 °C unless otherwise noted)							
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNITS
Diode forward voltage	V <sub>F</sub>	I <sub>F</sub> = 200 A	T <sub>J</sub> = 25 °C	ı	1.82	2.25	V
blode lorward voltage		IF = 200 A	T <sub>J</sub> = 125 °C	ı	1.95	ı	
Diode reverse recovery charge	Q <sub>rr</sub>	Q <sub>rr</sub>	$T_J = 25  ^{\circ}C$	-	16.6	-	
Diode reverse recovery charge			T <sub>J</sub> = 125 °C	-	29.2	-	μC
Diada park reverse recevem event	I <sub>rr</sub>	$I_F = 200 \text{ A}, V_R = 600 \text{ V},$ $dI/dt = -2370 \text{ A/}\mu\text{s},$	T <sub>J</sub> = 25 °C	-	156	-	Α
Diode peak reverse recovery current		$V_{GE} = -15 \text{ V}$	T <sub>J</sub> = 125 °C	-	210	-	
Diada rayaraa raaayany anaray	E <sub>rec</sub>	GE .	T <sub>J</sub> = 25 °C	-	9.3	-	mJ
Diode reverse recovery energy			T <sub>J</sub> = 125 °C	-	16.0	-	IIIJ



THERMAL AND MECHANICAL SPECIFICATIONS						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Operating junction temperature range	TJ		-	-	150	°C
Storage temperature range	T <sub>STG</sub>		-40	-	125	
Junction to case	Б		-	-	0.11	
Diode	$R_{thJC}$		-	-	0.14	K/W
Case to sink	R <sub>thCS</sub>	Conductive grease applied	-	0.035	-	
Mounting torque		Power terminal screw: M6	2.5 to 5.0		Nm	
		Mounting screw: M6	3.0 to 5.0		INIII	
Weight				300		g

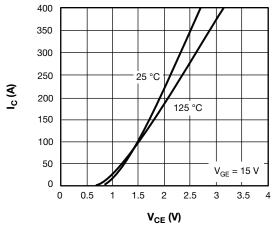


Fig. 1 - IGBT Typical Output Characteristics

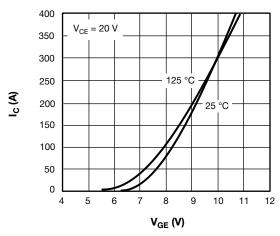


Fig. 2 - IGBT Typical Transfer Characteristics

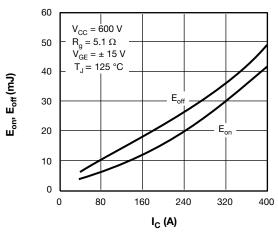


Fig. 3 - IGBT Switching Loss vs. I<sub>C</sub>

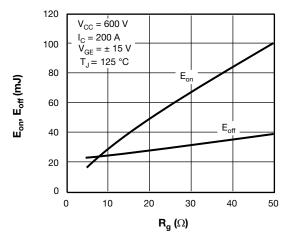
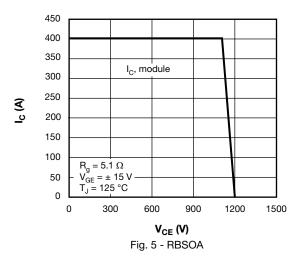


Fig. 4 - IGBT Switching Loss vs. Ra



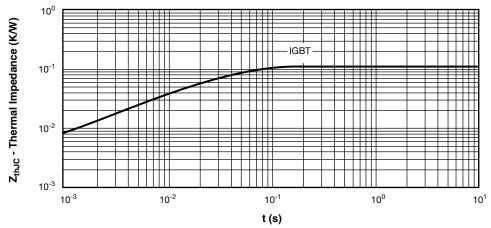


Fig. 6 - IGBT Transient Thermal Impedance

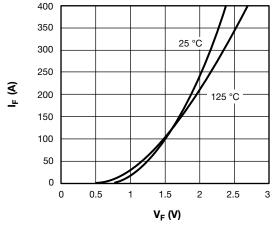


Fig. 7 - Diode Typical Forward Characteristics

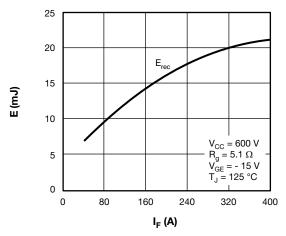


Fig. 8 - Diode Switching Loss vs. I<sub>F</sub>

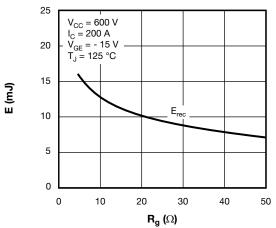


Fig. 9 - Diode Switching Loss vs. Gate Resistance Rg

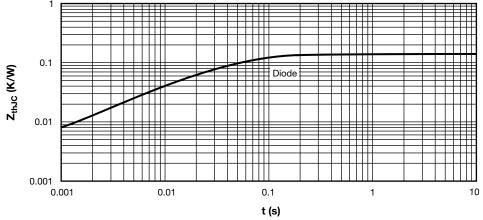
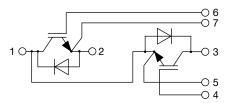


Fig. 10 - Diode Transient Thermal Impedance

### **CIRCUIT CONFIGURATION**

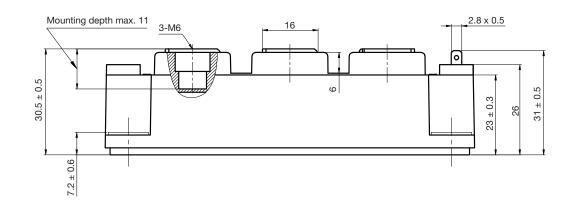


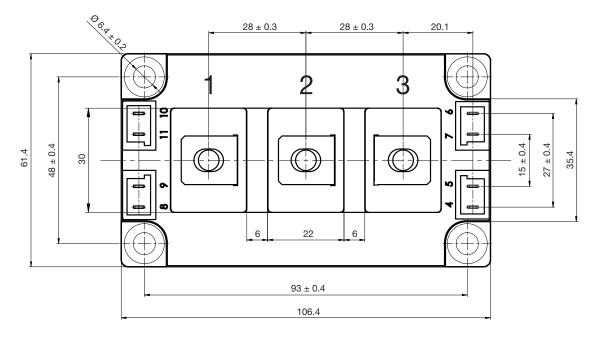
LINKS TO RELATED DOCUMENTS				
Dimensions	www.vishay.com/doc?95525			



## **Double INT-A-PAK**

### **DIMENSIONS** in millimeters (inches)







### **Legal Disclaimer Notice**

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